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PATENT ABSTRACTS OF JAPAN

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(21)Application number : 02-214563 (71)Applicant : AICA KOGYO CO LTD

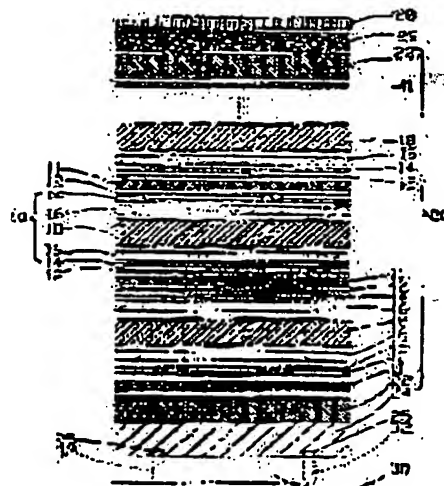
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(54) PREPARATION OF LAMINATED PRODUCT

(57)Abstract:

PURPOSE: To obtain a laminated product in high quality, a material suitable for use in a laminated substrate of an electronic part, by stacking laminated products in a clean room, carrying a stack of the laminated products by a conveyor out of the clean room, placing them in a platen, overlay them with a sealed covering outside the clean room and subjecting them to an autoclave molding wherein they are heated and pressed in a vacuum.

CONSTITUTION: A sublayer 18 is interposed between 2 pieces of preregs 16 and 16 and, on the outside thereof, 2 pieces of copper foils 14 and 14 are overlaid respectively. In substantially the same way, 2 pieces of release films 12 and 12 are overlaid on both the sides of the so obtained laminated product, followed by interposing the outsides thereof between 2 pieces of mirror plates 11 and 11. The sublayer 18 is made by applying a copper foil to a thin plate, printing a circuit on both the sides thereof, treating it with etching and subjecting both the sides thereof to a rough surface treatment. Moreover, after the copper foil 14 is molded, a circuit can be formed by means of



a printing and tching treatment. The release film 12 is capable of pr venting the resin from running off from the preregs 16. Th mirror plate 11 helping in th rmal conductivity concurrently can b p led off from the laminat d product 10 with ease after the laminated product is molded.

LEGAL STATUS

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